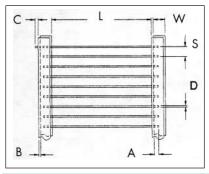
## Type JW

• Ideally suited for "Crossovers" or "Jumpers" on PCBs with Auto Insertion Capability.



Dimensions										
	L=LENGTH	S=SPACING	W=WIDTH	A	В	C				
inches	2.047±0.039	$0.200 \pm 0.016$	0.236±0.039	0.118 min.	.020 max.	0				
(mm)	52.00±1.00	5.00±0.40	6.00±1.00	3.00 min.	0.50 max.	0				

Part Number & Features									
Part Number	Type	(D) Diameter - Inches (mm)	Guage Ref.	Max. Current	Qty/Reel				
JW50 TR	JW50	$0.20 \pm .001 \ (0.50 \pm 0.02)$	24	2A	10,000 pcs.				
JW55 TR	JW55	$0.22 \pm .001 \ (0.55 \pm 0.03)$	23	3A	10,000 pcs.				
JW60 TR	JW60	$0.24 \pm .001 \; (0.60 \pm 0.30)$	22	3A	10,000 pcs.				
JW80 TR	JW80	0.31±.022 (0.80±0.25)	20	4A	10,000 pcs.				

## **CHARACTERISTICS**

TEST	TEST METHOD	LIMITS
RESISTANCE	<0.005 ohm	
OPERATING TEMPERATURE	-55°C ~ 155°C	
MAX. CURRENT	5 amps	
MAX. WORKING VOLTAGE	300Vdc	
MAX. OVERLOAD VOLTAGE	600Vdc	
TEMPERATURE COEFFICIENT	(ppm/°C) 0 ~ -100 ppm	
SHORT TIME OVERLOAD	HORT TIME OVERLOAD Apply 2.5 times the voltage rating for 5 seconds	
LOAD LIFE	1,000 hrs at 70°C a direct voltage applied, cycles of 1.5 hrs. on and 0.5 hrs. off throughout test.	<sup>3</sup> R=0.5%
TEMPERATURE CYCLING	TEMPERATURE CYCLING  5 cycles of 30 min. duration at the extremes of temperature range, maximum and minimum, measurement of ohmic value 4 hrs. after completion of test.	
DIELECTRIC STRENGTH	Using a 90° "V" shaped conductive block apply 100V minimum, increasing 100V/sec. for 5 seconds.	<sup>3</sup> R=0.5%
HUMIDITY	HUMIDITY 350 hrs. at 40°C, 90 to 95% RH	
SOLDERABILITY	Dipped in Sn/Pb (60/40) at 235°, 5 sec. 1.5mm from the body	95% of tested surface covered
VIBRATION	by MIL-STD-202, 201A	
TERMINAL ROBUSTNESS	Traction, applied 2.5kg. for 10 sec. Bends, 2 bends 90°C applying load to terminals of 0.5kg. Twist, 2 successive turns 180°, 6mm from body.	No visible damage
RESISTANCE TO SOLVENTS	RESISTANCE TO SOLVENTS  Trichlorethylene, TMC as the most aggressives for 60 sec. at boiling point.	

## **APPLICATIONS**

Molded jumper wires or crossovers, as they are sometimes called, are basically interconnection devices between points on a PC board. They are generally used for the following reasons:

- Inability to connect two points on a PC board due to other circuit paths which must be crossed over.
- An after-the-fact design change that requires new point connections.
- Circuit tuning by changing point connections.
- Optional feature applications.